

Abstract

This invention relates to a method for equalizing the thickness variation of a substrate stack (1) which consists of a product substrate (4) and a carrier substrate (2) and which is connected in particular by means of an interconnect layer (3), by local application of local thickness peaks (12) by means of an application apparatus (11, 11', 11'') which has at least one application unit (9, 9', 9'', 9''', 9^{IV}, 9^V, 9^{VI}).

Furthermore this invention relates to a corresponding device.

Figure 6b in this regard